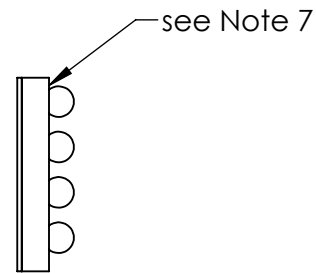
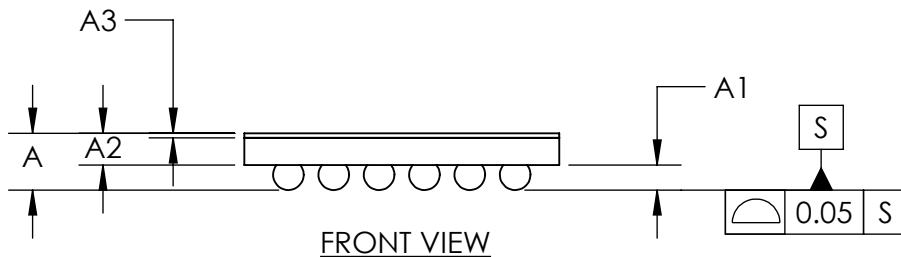


TOP VIEW

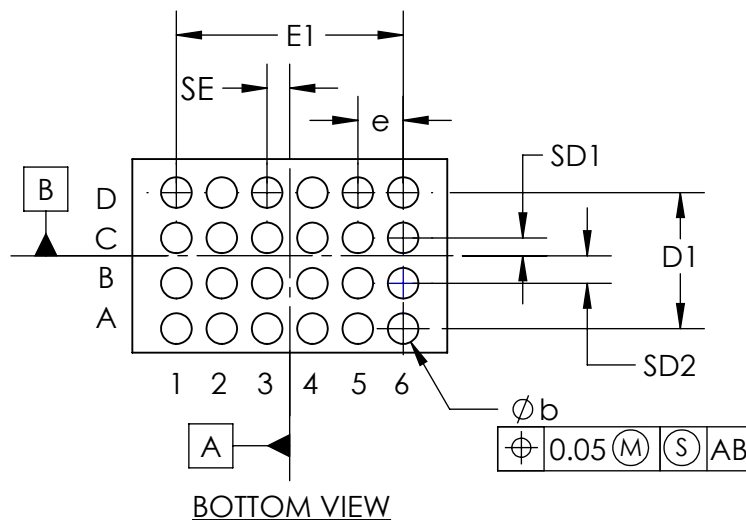


SIDE VIEW



FRONT VIEW

COMMON DIMENSIONS	
A	0.50 MAX
A1	0.19 ±0.03
A2	0.28 REF
A3	0.04* BASIC
b	∅0.27 ±0.03
D	1.708 ±0.025
E	2.778 ±0.025
D1	1.20 BASIC
E1	2.00 BASIC
e	0.40 BASIC
SD1	0.158 BASIC
SD2	0.242 BASIC
SE	0.20 BASIC
DEPOPULATED BUMPS: NONE	



BOTTOM VIEW

NOTES:

1. Terminal pitch is defined by terminal center to center value.
2. Outer dimension is defined by center lines between scribe lines.
3. All dimensions in millimeter.
4. Marking shown is for package orientation reference only.
5. Tolerance is ± 0.02 unless specified otherwise.
6. All dimensions apply to PbFree (+) package codes only.
7. Front - side finish can be either Black or Clear.
8. \*For 12" wafer, A3 = 0.025mm.

- DRAWING NOT TO SCALE -

 <b>maxim integrated™</b>	
TITLE PACKAGE OUTLINE 24 BUMPS THIN WLP PKG. 0.4 mm PITCH, N241A2+2	
APPROVAL	DOCUMENT CONTROL NO. 21-100370
REV. C	1/1